

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Metal oxide	Lead Dioxide (PbO2)	1309-60-0	0.00198	0.41	0.03362
	Doped silicon	Silicon (Si)	7440-21-3	0.4804	99.59	8.16638
			Subtotal	0.48238	100	8.2
Solder Wire	Tin alloy	Tin (Sn)	7440-31-5	0.01553	5.0	0.26403
	Silver alloy	Silver (Ag)	7440-22-4	0.00466	1.5	0.07921
	Lead alloy	Lead (Pb)	7439-92-1	0.29045	93.5	4.93735
			Subtotal	0.31064	100	5.28059
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.48027	100.0	8.16423
			Subtotal	0.48027	100	8.16423
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.06483	0.1	1.102
	Copper alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	0.01945	0.03	0.3306
	Copper alloy	Copper (Cu)	7440-50-8	64.7425	99.87	1100.5674
			Subtotal	64.82678	100	1102
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.13354	100.0	2.27
			Subtotal	0.13354	100	2.27
Mould Compound	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	1.51949	4.5	25.83
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	3.37664	10.0	57.4
	Filler	Silica fused	60676-86-0	25.3248	75.0	430.5
	Metal hydroxide	Metal hydroxide		3.37664	10.0	57.4
	Carbon Black	Carbon black	1333-86-4	0.16883	0.5	2.87
			Subtotal	33.7664	100	574
			Total	100.00001	100	1699.91482

Disclaimer

All information in this document is furnished for exploratory or indicative purposes only. All information in this document is believed to be accurate and reliable. However, WeEn Semiconductors does not give any representations or warranties as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. WeEn Semiconductors may make changes to information published in this document at any time and without notice. Minor deviations may occur in the products from different manufacturing location. This document supersedes and replaces all information supplied prior to the publication hereof. Nothing in this document may be interpreted or construed as an offer to sell products that is open for acceptance or the grant, conveyance or implication of any license under any copyrights, patents or other industrial or intellectual property rights.